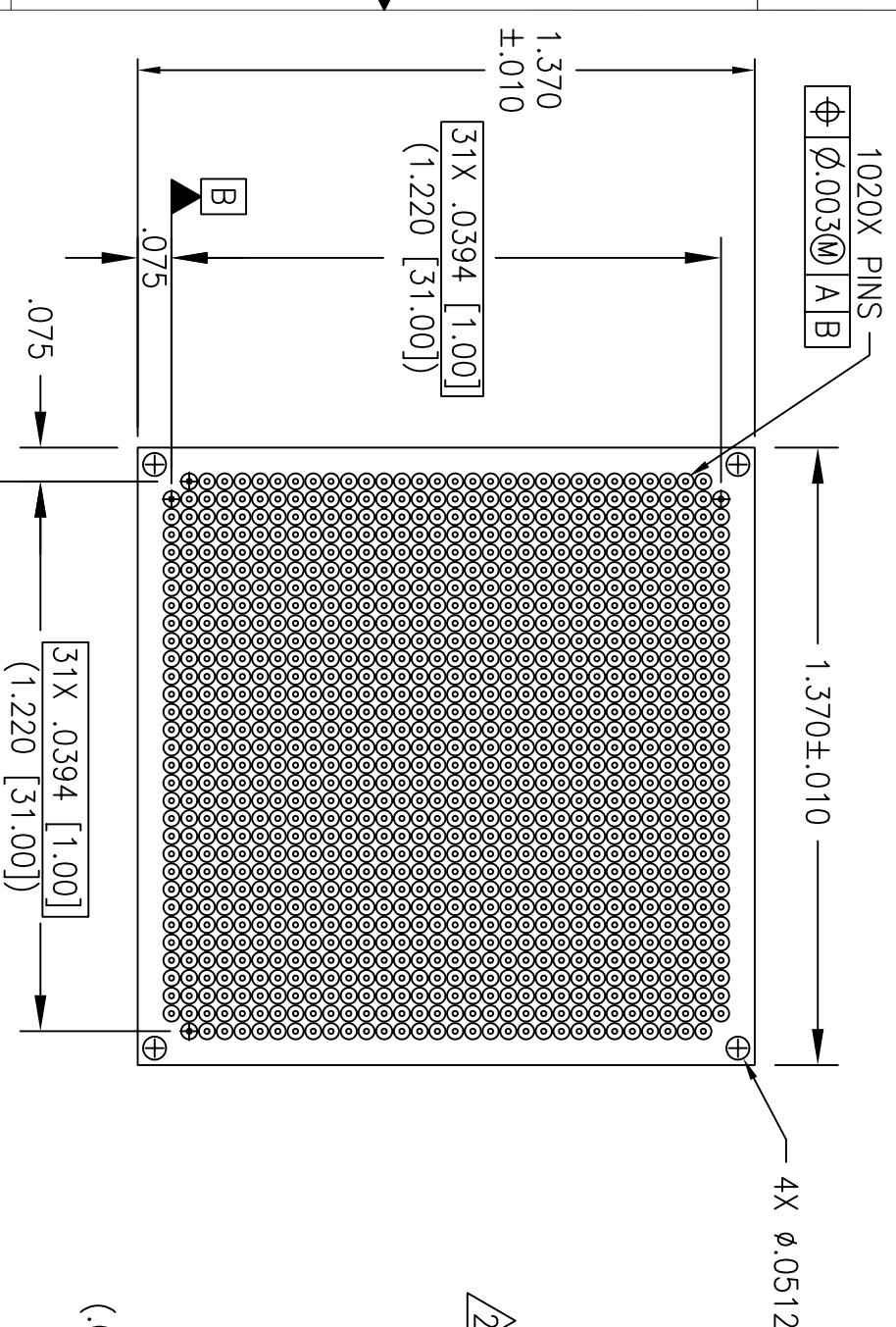


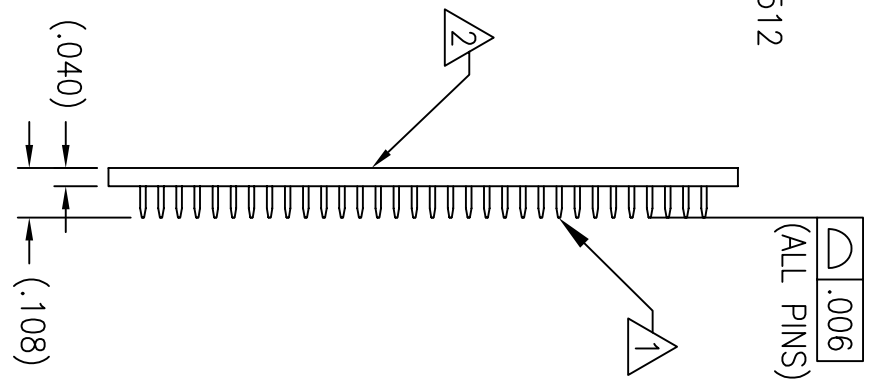
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REV	DESCRIPTION	EGN	DATE	RELEASE
1	SALES RELEASE			

TOP VIEW



RS VIEW



NOTES:

1. PINS ϕ .0117
MATERIAL: PHOSPHOR BRONZE.
PLATING: HARD GOLD OVER NICKEL.
2. INSULATOR MATERIAL: FR4.

CONTRACT NO.		TITLE	
DRAWN BY		HIL0-BGA PIN BASE	
DESIGNER		32 X 32, 1020 PINS	
CHECKER		1mm PITCH	
DATE	DATE	DATE	DATE
UNLESS OTHERWISE SPECIFIED:	DIMENSIONS ARE IN INCHES	TOLERANCES:	±
ANGLES: \pm 1/64	FRACTIONS: 1/16	DECIMALS: \pm 0.010	XXX \pm 0.005
XXX	.XXX	.XXX	\pm 0.005
DATE	DATE	DATE	DATE
PROCESS ENG.	DATE	DATE	DATE
SAVED AS: HLP-321020-B-10.DWG	SCALE	DRAWING NO.	REV
FINISHED ASST: HLP-321020-B-10	N/A	HLP-321020-B-10	1

INTERCONNECT SYSTEMS INC.
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